

ABSTRACT OF THE DISCLOSURE

A metal polishing slurry having a static etch inhibitor and method for polishing a substrate while inhibiting static etching during the polishing of a substrate. The slurry composition includes an iodate-free halogenated

5 inhibiting compound added to a generic slurry to form a resultant slurry.

The substrate is polished using the resultant slurry, which inhibits the static etching of the substrate being polished. Also provided is a metal polishing slurry for inhibiting static etch comprising an oxidizer, a complexing agent, and an iodate-free halogenated inhibiting compound.

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